L Number	Hits	Search Text	DB	Time stamp
1	13999	((438/622) or (438/625) or (438/626) or	USPAT;	2004/09/02
*	13333	(438/627) or (438/628) or (438/629) or	US-PGPUB;	14:31
		(438/631) or (438/633) or (438/634) or	EPO; JPO;	
		(438/637) or (438/638) or (438/643) or	DERWENT;	
		(438/644) or (438/645) or (438/648) or	IBM TDB	
ł		(438/652) or (438/653) or (438/654) or	1511_155	
1		(438/656) or (438/669) or (438/672) or		
		(438/685) or (438/687) or (438/691) or		
		(438/692) or (438/695) or (438/697) or		
	į	(438/700)).CCLS.		
2	88	(((438/622) or (438/625) or (438/626) or	USPAT;	2004/09/02
_		(438/627) or (438/628) or (438/629) or	US-PGPUB;	14:33
		(438/631) or (438/633) or (438/634) or	EPO; JPO;	133
		(438/637) or (438/638) or (438/643) or	DERWENT;	
		(438/644) or (438/645) or (438/648) or	IBM TDB	
		(438/652) or (438/653) or (438/654) or	1211_122	
		(438/656) or (438/669) or (438/672) or		
		(438/685) or (438/687) or (438/691) or		
	j	(438/692) or (438/695) or (438/697) or		
		(438/700)).CCLS.) and (electropolish\$3 or		
	ļ	(electrolytic adj etch\$3) or (electro adj		
		planariz\$5))		
3	57	((((438/622) or (438/625) or (438/626) or	USPAT;	2004/09/02
-		(438/627) or (438/628) or (438/629) or	US-PGPUB;	14:33
		(438/631) or (438/633) or (438/634) or	EPO; JPO;	
		(438/637) or (438/638) or (438/643) or	DERWENT;	
		(438/644) or (438/645) or (438/648) or	IBM TDB	
		(438/652) or (438/653) or (438/654) or		
		(438/656) or (438/669) or (438/672) or		
		(438/685) or (438/687) or (438/691) or		
		(438/692) or (438/695) or (438/697) or		
		(438/700)).CCLS.) and (electropolish\$3 or		
		(electrolytic adj etch\$3) or (electro adj		
		planariz\$5))) and (barrier near2 layer)		
4	8	(((((438/622) or (438/625) or (438/626)	USPAT;	2004/09/02
		or (438/627) or (438/628) or (438/629) or	US-PGPUB;	14:55
		(438/631) or (438/633) or (438/634) or	EPO; JPO;	
		(438/637) or (438/638) or (438/643) or	DERWENT;	
		(438/644) or (438/645) or (438/648) or	IBM_TDB	
		(438/652) or (438/653) or (438/654) or		
		(438/656) or (438/669) or (438/672) or	1	
		(438/685) or (438/687) or (438/691) or		
		(438/692) or (438/695) or (438/697) or		
1		(438/700)).CCLS.) and (electropolish\$3 or		
		(electrolytic adj etch\$3) or (electro adj		
1	İ	planariz\$5))) and (barrier near2 layer))		
1		and ((electropolish\$3 or (electrolytic		
		adj etch\$3) or (electro adj planariz\$5)) near5 (barrier adj layer))		
5	2	nears (barrier adj layer) (((((438/622) or (438/625) or (438/626)	HCDAM.	2004/00/02
3			USPAT; US-PGPUB;	2004/09/02 15:13
		or (438/627) or (438/628) or (438/629) or (438/631) or (438/633) or (438/634) or	EPO; JPO;	13:13
1		(438/637) or (438/638) or (438/643) or	DERWENT;	
		(438/644) or (438/645) or (438/648) or	IBM TDB	
		(438/652) or (438/653) or (438/654) or	1257-125	
1		(438/656) or (438/669) or (438/672) or		
		(438/685) or (438/687) or (438/691) or		
	}	(438/692) or (438/695) or (438/697) or		
		(438/700)).CCLS.) and (electropolish\$3 or		
		(electrolytic adj etch\$3) or (electro adj		
		planariz\$5))) and (barrier near2 layer))		
		and ((electropolish\$3 or (electrolytic		
		adj etch\$3) or (electro adj planariz\$5))		
		near5 (barrier adj layer))) and adhesion		
6	1	("6176992").PN.	USPAT	2004/09/02
				15:13

			r	1 0000 /00 /00
_	7312	("0000650").PN. or ((438/678) or (438/679) or (438/438/627) or (438/653) or (438/656) or (438/643) or (438/648) or (438/685) or (438/686) or (438/633) or (438/687) or (438/638)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04
_	79		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 02:04
-	73	((("0000650").PN. or ((438/678) or (438/679) or (438/438/627) or (438/653) or (438/656) or (438/643) or (438/685) or (438/686) or (438/633) or (438/687) or (438/637) or (438/638)).CCLS.) and barrier and electrolyt\$5 and potential) and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 02:04
_	4	(((("0000650").PN. or ((438/678) or (438/679) or (438/438/627) or (438/653) or (438/656) or (438/643) or (438/648) or (438/685) or (438/686) or (438/633) or (438/687) or (438/637) or (438/638)).CCLS.) and barrier and electrolyt\$5 and potential) and (copper or cu)) and (electrolyt\$5 same (koh or (potassium adj hydroxide) or naoh or (sodium adj hydroxide) or (ammonium adj hydroxide) or (h adj2 oh) or (tetra adj2 methyl adj ammonium and hydroxide) or tmah))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04
-	4	((((("0000650").PN. or ((438/678) or (438/679) or (438/438/627) or (438/653) or (438/656) or (438/643) or (438/648) or (438/685) or (438/686) or (438/633) or (438/687) or (438/637) or (438/638)).CCLs.) and barrier and electrolyt\$5 and potential) and (copper or cu)) and (electrolyt\$5 same (koh or (potassium adj hydroxide) or naoh or (sodium adj hydroxide) or (ammonium adj hydroxide) or (tetra adj2 methyl adj ammonium and hydroxide) or tmah))) and ph	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04
-	8776	damascene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 02:17
-	5486	damascene and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/04 02:17
-	1668	(damascene and copper) and barrier and seed	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/04 02:17
-	877	((damascene and copper) and barrier and seed) and adhesion	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 02:18

				· · · · · · · · · · · · · · · · · · ·
-	687	(((damascene and copper) and barrier and	USPAT;	2003/12/04
		seed) and adhesion) and ((expos\$4 same	US-PGPUB;	02:19
		barrier) or ((etch\$4 or remove) same	EPO; JPO;	
		seed))	DERWENT;	
			IBM_TDB	
-	168	((((damascene and copper) and barrier and	USPAT;	2003/12/04
		seed) and adhesion) and ((expos\$4 same	US-PGPUB;	02:20
		barrier) or ((etch\$4 or remove) same	EPO; JPO;	
		seed))) and (electrolyte or electrolyt\$3)	DERWENT;	
			IBM TDB	
	71	((((damascene and copper) and barrier	USPAT;	2003/12/04
		and seed) and adhesion) and ((expos\$4	US-PGPUB;	02:20
		same barrier) or ((etch\$4 or remove) same	EPO; JPO;	
		seed))) and (electrolyte or	DERWENT;	
		electrolyt\$3)) and potential	IBM TDB	
_	10	(((((damascene and copper) and barrier	USPAT;	2003/12/04
		and seed) and adhesion) and ((expos\$4	US-PGPUB;	02:20
		same barrier) or ((etch\$4 or remove) same	EPO; JPO;	
		seed))) and (electrolyte or	DERWENT;	
		electrolyt\$3)) and potential) and	IBM_TDB	
		(electrolyt\$5 same (koh or (potassium adj		
		hydroxide) or naoh or (sodium adj		
		hydroxide) or (ammonium adj hydroxide) or		
		(nh adj2 oh) or (tetra adj2 methyl adj		
		ammonium and hydroxide) or tmah))		
_	5	((((((damascene and copper) and barrier	USPAT;	2003/12/04
		and seed) and adhesion) and ((expos\$4	US-PGPUB;	02:22
		same barrier) or ((etch\$4 or remove) same	EPO; JPO;	******
		seed))) and (electrolyte or	DERWENT;	
		electrolyt\$3)) and potential) and	IBM TDB	
i		(electrolyt\$5 same (koh or (potassium adj	1511_155	
		hydroxide) or naoh or (sodium adj		
		hydroxide) or (ammonium adj hydroxide) or		
1	1	(nh adj2 oh) or (tetra adj2 methyl adj		
		ammonium and hydroxide) or tmah))) and ph		
_	5	((((((damascene and copper) and barrier	USPAT;	2003/12/04
		and seed) and adhesion) and ((expos\$4	US-PGPUB;	02:22
		same barrier) or ((etch\$4 or remove) same	EPO; JPO;	02.22
		seed))) and (electrolyte or	DERWENT;	
		electrolyt\$3)) and potential) and	IBM TDB	
		(electrolyt\$5 same (koh or (potassium adj	1511_155	
		hydroxide) or naoh or (sodium adj		
		hydroxide) or (ammonium adj hydroxide) or		
		(nh adj2 oh) or (tetra adj2 methyl adj		
		ammonium and hydroxide) or tmah))) not		
		(((((((damascene and copper) and barrier		
		and seed) and adhesion) and ((expos\$4		
	1	same barrier) or ((etch\$4 or remove) same		
	1	same parrier; or ((etch34 or remove) same seed))) and (electrolyte or		
	1			
	1	electrolyt\$3)) and potential) and (electrolyt\$5 same (koh or (potassium adj		
	1			
	1	hydroxide) or naoh or (sodium adj		
	1	hydroxide) or (ammonium adj hydroxide) or		
	1	(nh adj2 oh) or (tetra adj2 methyl adj		
	1	ammonium and hydroxide) or tmah))) and		
		ph)	TTG DAM	2004/06/04
_	2	(("20020074238") or ("20030207558")).PN.	USPAT;	2004/06/04
L	1 .	I	US-PGPUB	13:57